# **Power MOSFET**

# 30 V, 1.7 A, Single N-Channel, SC-70

#### **Features**

- Low On-Resistance
- Low Gate Threshold Voltage
- Halide Free
- This is a Pb-Free Device

#### **Applications**

- Low Side Load Switch
- DC-DC Converters (Buck and Boost Circuits)
- Optimized for Battery and Load Management Applications in Portable Equipment like Cell Phones, PDA's, Media Players, etc.

## MAXIMUM RATINGS (T<sub>.1</sub> = 25°C unless otherwise noted)

Paramo	Symbol	Value	Unit			
Drain-to-Source Voltage	$V_{DSS}$	30	V			
Gate-to-Source Voltage			V <sub>GS</sub>	±12	V	
Continuous Drain	Steany A			1.6		
Current (Note 1)	State	T <sub>A</sub> = 85°C	$I_{D}$	1.13	Α	
	t ≤ 5 s	T <sub>A</sub> = 25°C		1.70		
Power Dissipation	Steady			0.294		
(Note 1)	State	$T_A = 25^{\circ}C$	$P_{D}$		W	
	t ≤ 5 s			0.350		
Pulsed Drain Current	Pulsed Drain Current $t_p = 10 \mu s$			3.4	Α	
Operating Junction and S	T <sub>J</sub> ,	-55 to	°C			
	T <sub>stg</sub>	150				
Source Current (Body Dic	I <sub>S</sub>	0.25	Α			
Lead Temperature for Sol (1/8" from case for 10 s)	T <sub>L</sub>	260	°C			

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

#### THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Ambient - Steady State (Note 1)	$R_{\theta JA}$	425	°C/W
Junction-to-Ambient – $t \le 5 s$ (Note 1)	$R_{\theta JA}$	360	

<sup>1.</sup> Surface-mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [2 oz] including traces)

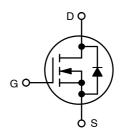


## ON Semiconductor®

#### http://onsemi.com

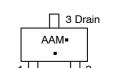
V <sub>(BR)DSS</sub> R <sub>DS(on)</sub> MAX		I <sub>D</sub> MAX
30 V	93 mΩ @ 10 V	1.7 A
	100 mΩ @ 4.5 V	1.5 A
	140 mΩ @ 2.5 V	1.0 A

## SC-70/SOT-323 (3 LEADS)





SC-70/SOT-323 **CASE 419** STYLE 8



Source

**MARKING DIAGRAM/ PIN ASSIGNMENT** 

AΑ = Specific Device Code = Date Code\* M

= Pb-Free Package

(Note: Microdot may be in either location)

Gate

## **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NTS4172NT1G	SC-70 (Pb-Free)	3000/Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

<sup>\*</sup> Date code orientation may vary depending upon manufacturing location

# $\textbf{MOSFET ELECTRICAL CHARACTERISTICS} \ (T_J = 25^{\circ}\text{C unless otherwise noted})$

Parameter	Symbol	Test Condition	on Min Ty		Тур Мах	Units	
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	30			٧	
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> /T <sub>J</sub>	I <sub>D</sub> = 250 μA, Reference to 25°C		8.4		mV/°C	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 24 V, T <sub>J</sub> = 25°C V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 24 V, T <sub>J</sub> = 125°C			1.0 5.0	μΑ	
Gate-to-Source Leakage Current	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$			±100	nA	
ON CHARACTERISTICS (Note 3)	•		•		•	•	
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{GS} = V_{DS}, I_D = 250 \mu A$	0.6	1.0	1.4	V	
Negative Threshold Temperature Coefficient	V <sub>GS(TH)</sub>			3.1		mV/°C	
Drain-to-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 1.7 A		58	93	mΩ	
		V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 1.5 A		64	100		
		V <sub>GS</sub> = 2.5 V, I <sub>D</sub> = 1.0 A		79	140		
Forward Transconductance	9FS	V <sub>DS</sub> = 5.0 V, I <sub>D</sub> = 1.7 A		4.2		S	
CHARGES, CAPACITANCES AND GA	TE RESISTA	NCE	•			-	
Input Capacitance	C <sub>iss</sub>			381		pF	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 \text{ V, f} = 1.0 \text{ MHz,}$ $V_{DS} = 15 \text{ V}$		39.6			
Reverse Transfer Capacitance	C <sub>rss</sub>	VDS - 13 V		32.6			
Total Gate Charge	Q <sub>G(TOT)</sub>			4.38		nC	
Threshold Gate Charge	Q <sub>G(TH)</sub>	V <sub>GS</sub> = 4.5 V, V <sub>DS</sub> = 15 V,		0.40			
Gate-to-Source Charge	$Q_{GS}$	$I_D = 1.7 \text{ A}$		0.62		1	
Gate-to-Drain Charge	$Q_{GD}$			1.33			
Gate Resistance	$R_{G}$			4.5		Ω	
SWITCHING CHARACTERISTICS (No	ote 4)				1		
Turn-On Delay Time	t <sub>d(on)</sub>			7.5		ns	
Rise Time	t <sub>r</sub>	V <sub>G</sub> e = 4.5 V. V <sub>DD</sub> = 15 V.		4.4			
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS}$ = 4.5 V, $V_{DD}$ = 15 V, $I_{D}$ = 1.7 A, $R_{G}$ = 3 $\Omega$		16.1			
Fall Time	t <sub>f</sub>			2.2			
DRAIN-SOURCE DIODE CHARACTE	RISTICS				1		
Forward Diode Voltage	$V_{SD}$	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 1.0 A		0.76	1.0	V	
Reverse Recovery Time	t <sub>RR</sub>			7.9		ns	
Charge Time	ta	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 1.0 A,		5.0		1	
Discharge Time	t <sub>b</sub>	$dI_{SD}/d_t = 100 \text{ A/}\mu\text{s}$		2.9		1	
Reverse Recovery Charge	Q <sub>RR</sub>			2.0		nC	

Surface-mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [2 oz] including traces)
Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%
Switching characteristics are independent of operating junction temperatures

### TYPICAL CHARACTERISTICS

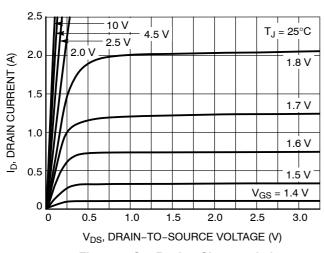


Figure 1. On-Region Characteristics

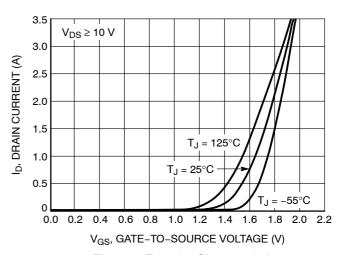


Figure 2. Transfer Characteristics

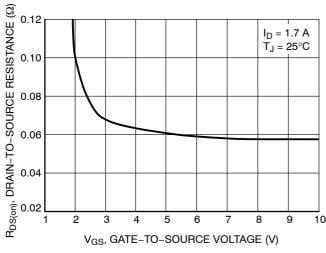


Figure 3. On-Resistance vs. Gate Voltage

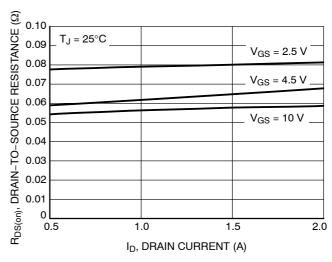


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

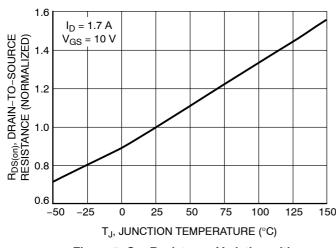


Figure 5. On–Resistance Variation with Temperature

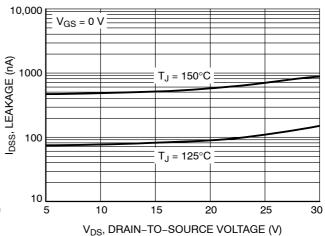


Figure 6. Drain-to-Source Leakage Current vs. Voltage

## **TYPICAL CHARACTERISTICS**

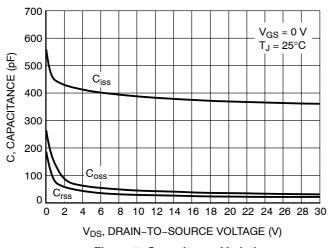


Figure 7. Capacitance Variation

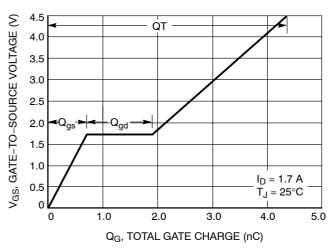


Figure 8. Gate-to-Source Voltage vs. Total Charge

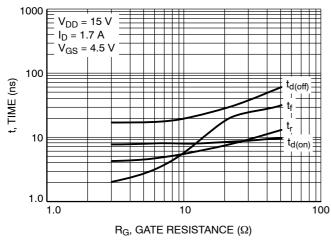


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

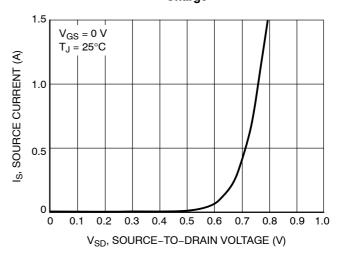


Figure 10. Diode Forward Voltage vs. Current





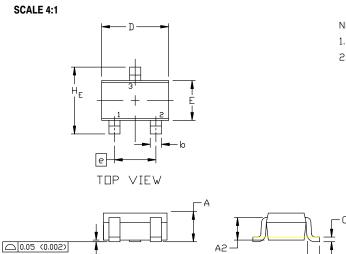
SC-70 (SOT-323) **CASE 419** ISSUE R

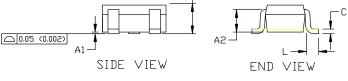
**DATE 11 OCT 2022** 

#### NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCH

	MILLIMETERS			INCHES			
	MILLIMETERS			INCHES			
DIM	MIN.	N□M.	MAX.	MIN.	N□M.	MAX.	
Α	0.80	0.90	1.00	0.032	0.035	0.040	
A1	0.00	0.05	0.10	0.000	0.002	0.004	
A2		0.70 REF			0.028 BSC		
b	0.30	0.35	0.40	0.012	0.014	0.016	
С	0.10	0.18	0.25	0.004	0.007	0.010	
D	1.80	2.00	2.20	0.071	0.080	0.087	
E	1.15	1.24	1.35	0.045	0.049	0.053	
е	1.20	1.30	1.40	0.047	0.051	0.055	
e1	0.65 BSC				0.026 BS	C	
L	0.20	0.38	0.56	0.008	0.015	0.022	
HE	2.00	2.10	2.40	0.079	0.083	0.095	





## **GENERIC MARKING DIAGRAM**



= Specific Device Code XX

Μ = Date Code

= Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

0.65 [0.025]
1.90 [0.075]
0.90 [0.035]
0.70 [0.028]

For additional information on our Pb-Free strategy and soldering details, please download the IN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

SOLDERING FOOTPRINT

STYLE 1: CANCELLED	STYLE 2: PIN 1. ANODE 2. N.C. 3. CATHODE	STYLE 3: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 4: PIN 1. CATHODE 2. CATHODE 3. ANODE	STYLE 5: PIN 1. ANODE 2. ANODE 3. CATHODE	
STYLE 6:	STYLE 7:	STYLE 8:	STYLE 9:	STYLE 10:	STYLE 11:
PIN 1. EMITTER	PIN 1. BASE	PIN 1. GATE	PIN 1. ANODE	PIN 1. CATHODE	PIN 1. CATHODE
2. BASE	2. EMITTER	2. SOURCE	2. CATHODE	2. ANODE	<ol><li>CATHODE</li></ol>
<ol><li>COLLECTOR</li></ol>	<ol><li>COLLECTOR</li></ol>	3. DRAIN	<ol><li>CATHODE-ANODE</li></ol>	3. ANODE-CATHODE	<ol><li>CATHODE</li></ol>

DOCUMENT NUMBER:	98ASB42819B	Electronic versions are uncontrolled except when accessed directly from the Document Repositor Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.		
DESCRIPTION:	SC-70 (SOT-323)		PAGE 1 OF 1	

onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. **onsemi** does not convey any license under its patent rights or the rights of others.

onsemi, Onsemi, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at <a href="www.onsemi.com/site/pdf/Patent-Marking.pdf">www.onsemi.com/site/pdf/Patent-Marking.pdf</a>. Onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA class 3 medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase

#### ADDITIONAL INFORMATION

**TECHNICAL PUBLICATIONS:** 

 $\textbf{Technical Library:} \ \underline{www.onsemi.com/design/resources/technical-documentation}$ 

onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at

www.onsemi.com/support/sales